

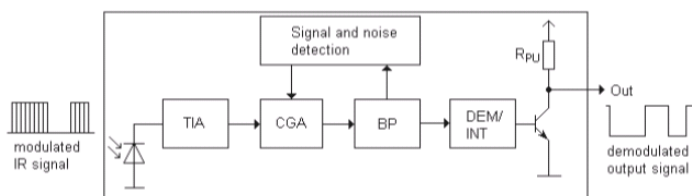
### Infrared Receiver Module IRM-V8XXJ2-C/TR1(HKC) Series



Pin Configuration

1. GND
2. VCC
3. OUT
4. GND

Block Diagram



16686

### Features

- Available for various carrier frequencies
- Min burst length: 150 us
- Min gap length: 275 us
- Low operating voltage
- High immunity against ambient light
- Long reception range
- High sensitivity
- Pb free and RoHS compliant
- Compliance with EU REACH.
- Compliance Halogen Free (Br < 900 ppm, Cl < 900 ppm, Br+Cl < 1500 ppm)

### Description

The device is miniature SMD type infrared receiver that has been developed and designed by using the latest IC technology.

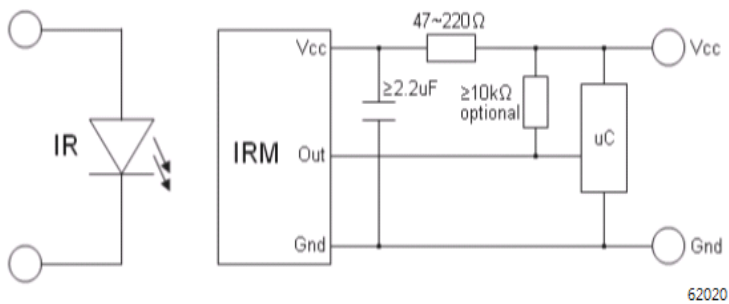
The PIN diode and preamplifier are assembled onto a lead frame and molded into an epoxy package which operated an IR filter.

The demodulated output signal can directly be decoded by a microprocessor.

## Applications

- Light detecting portion of remote control
- AV instruments such as Audio, TV, VCR, CD, MD, etc
- Home appliances such as Air-conditioner, Fan, etc
- Other devices using IR remote control
- CATV set top boxes
- Multi-media Equipment

## Application Circuit



## Parts Table

Model No.	Carrier Frequency
IRM-V838J2-C/TR1(HKC)	38 kHz

## Absolute Maximum Ratings (Ta=25°C) <sup>\*1</sup>

Parameter	Symbol	Rating	Unit
Supply Voltage	V <sub>CC</sub>	6	V
Operating Temperature	T <sub>opr</sub>	-20 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	°C
Reflow Temperature <sup>*2</sup>	T <sub>ref</sub>	260	°C

<sup>\*1</sup> Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

<sup>\*2</sup> Soldering time < 5 seconds

## Electro-Optical Characteristics (Ta=25°C and V<sub>CC</sub>=3.0V)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Current consumption	I <sub>CC</sub>	-	0.4	0.8	mA	No input signal
Supply voltage	V <sub>CC</sub>	2.7	-	5.5	V	
Peak wavelength	λ <sub>p</sub>	---	940	---	nm	
Reception range	L <sub>0</sub>	8	---	---	m	See chapter 'Test method' <sup>*3</sup>
	L <sub>45</sub>	5	---	---	m	
Half angle(horizontal)	φ <sub>h</sub>	---	±45	---	deg	
Half angle(vertical)	φ <sub>v</sub>	---	±45	---	deg	
High level pulse width	T <sub>H</sub>	400	---	800	μs	Test signal according to figure 1 <sup>*4</sup>
Low level pulse width	T <sub>L</sub>	400	---	800	μs	
High level output voltage	V <sub>OH</sub>	V <sub>CC</sub> -0.4	---	---	V	I <sub>SOURCE</sub> ≤ 1μA
Low level output voltage	V <sub>OL</sub>	---	0.2	0.5	V	I <sub>SINK</sub> ≤ 2mA

<sup>\*2</sup> The ray receiving surface at a vertex and relation to the ray axis in the range of θ=0° and θ=45°.

<sup>\*3</sup> A range from 30cm to the arrival distance. Average value of 50 pulses.

## Test method

The specified electro-optical characteristics are valid under the following conditions.

1. Measurement environment

A place without extreme light reflections.

2. External light

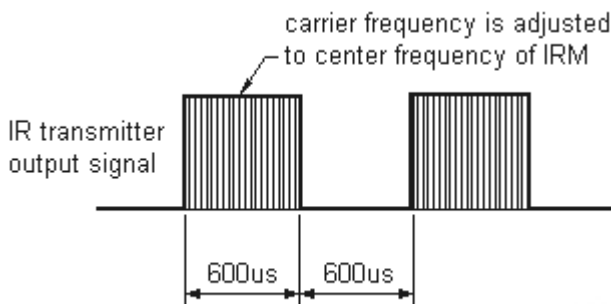
The environment contains an ordinary, white fluorescent lamp without high frequency modulation. The color temperature is 2856K and the illumination at the IR receiver is less than 10 Lux ( $E_v \leq 10\text{Lux}$ ).

3. Standard transmitter

The test transmitter is calibrated by using the circuit shown in figure 2. The radiation intensity of the transmitter is adjusted until  $V_o=400\text{mVp-p}$ . Both the test transmitter and the photo diode have the peak wavelength of 940nm. The photo diode for calibration is PD438B ( $\lambda_p=940\text{nm}$ ,  $V_r=5\text{V}$ ).

4. The measurement system is shown in Fig.-3

Fig.-1 Transmitter Wave Form



D.U.T output Pulse

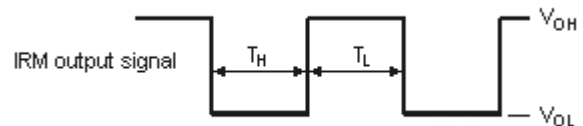


Fig.-2 Standard transmitter calibration

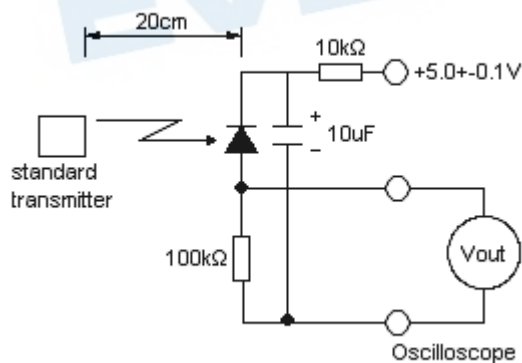
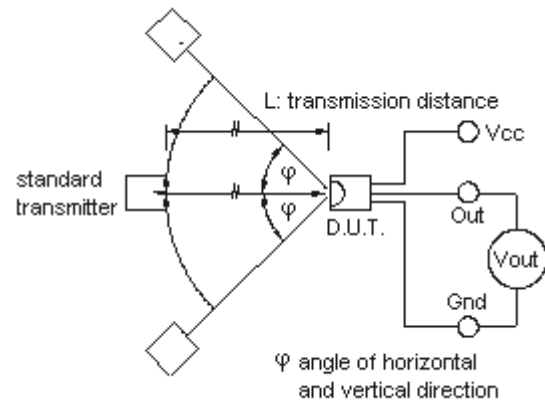
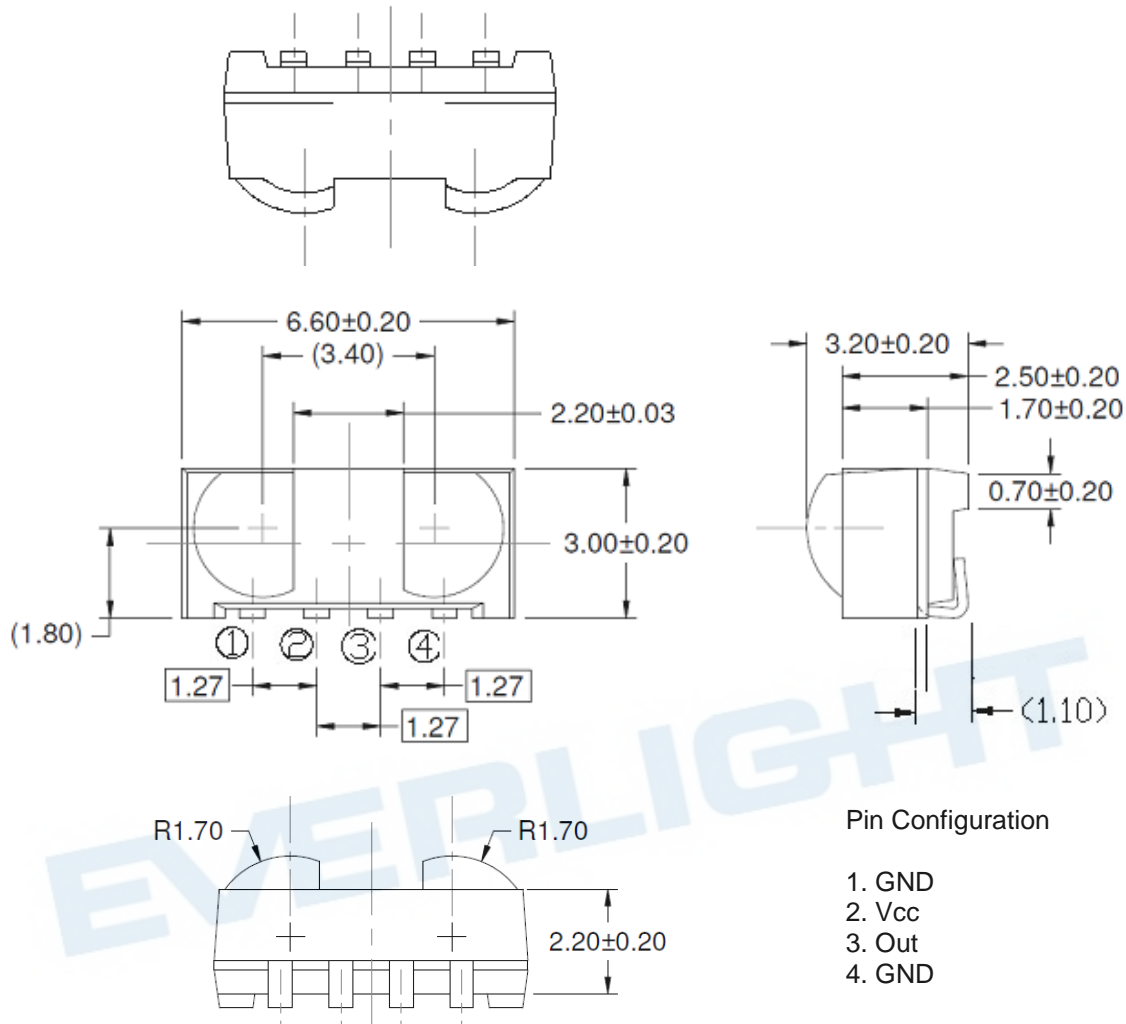


Fig.-3 Measuring System



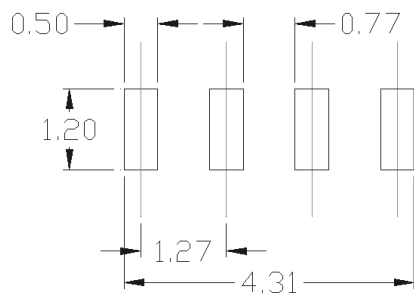
**Package Dimension**  
(Dimensions in mm)



Note: Tolerances unless mentioned  $\pm 0.5$ mm. Unit: mm

**Recommend soldering patterns**

The following soldering patterns are recommended for reflow-soldering



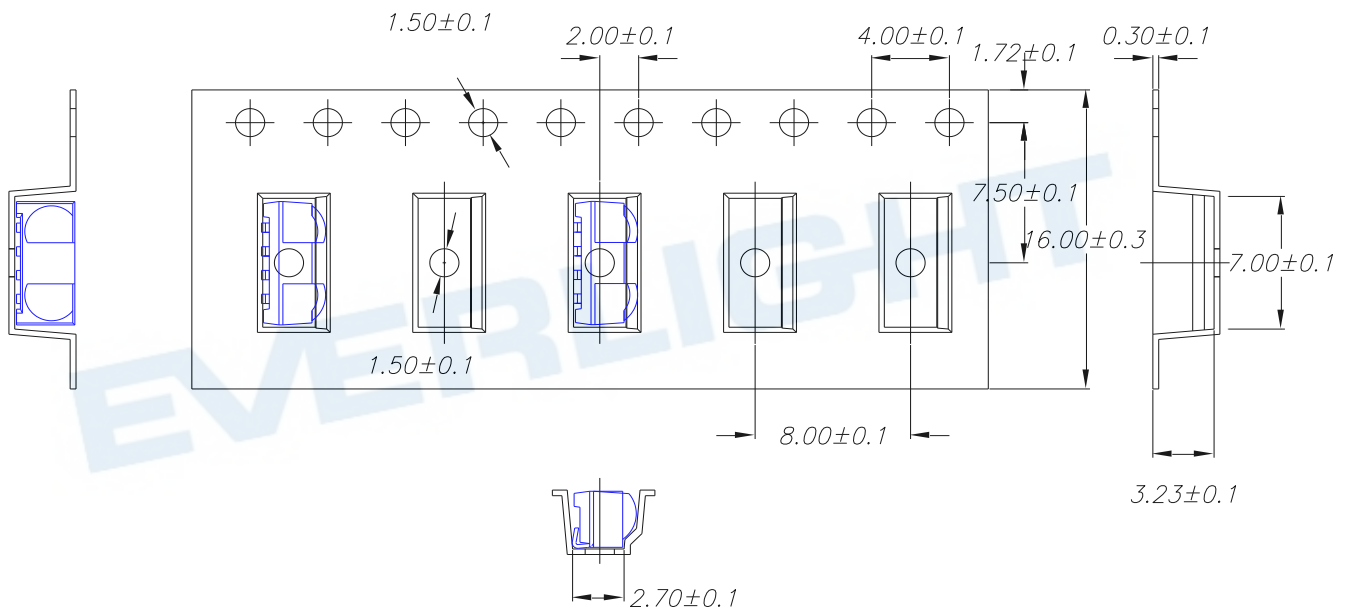
Note: Suggested pad dimension is just for reference only.  
Please modify the pad dimension based on individual need.

## Code information

Protocol	Suitable	Protocol	Suitable
NEC	Yes	Sony 12 bit	Yes
RC5	Yes	Sony 15 bit	Yes
RC6	Yes	Sony 20 bit	Yes*
RCMM	Yes	XMP	Yes
Toshiba	Yes	Continuous Code	No

\* Data must contain at least 4 logical 0 to ensure continuous data reception. If data contains less than 4 logical 0, single button press is supported, but continuous reception is not possible.

## Tape & Reel Packing Specifications



## Packing Quantity

2000 pcs / Reel  
5 Reels / Carton

### Recommended method of storage

The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

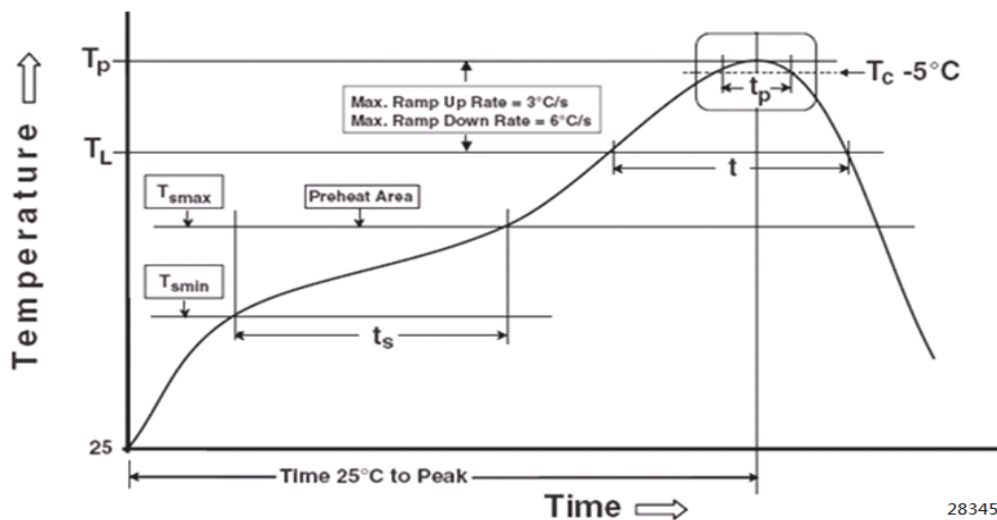
1. Shelf life in sealed bag from the bag seal date: 12 months at  $< 40^{\circ}\text{C}$  and  $< 90\%$  relative humidity (RH)
2. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be mounted within 72 hours of factory conditions  $< 30^{\circ}\text{C}/60\%\text{RH}$ .
3. If the moisture absorbent material (silica gel) has faded away or the IRM has exceeded the storage time. Baking treatment is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the conditions:  $60\pm 5^{\circ}\text{C}$  for 96 hours.

### ESD Precaution

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.

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## Solder Reflow Temperature Profile



Note:

Reference: IPC/JEDEC J-STD-020D

### Preheat

Temperature min ( $T_{smin}$ )	150 °C
Temperature max ( $T_{smax}$ )	200°C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max

### Other

Liquidus Temperature ( $T_L$ )	217 °C
Time above Liquidus Temperature ( $t_L$ )	60-100sec
Peak Temperature ( $T_p$ )	260°C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max.
Reflow times	2 times

Note:

1. Suggest that reflow soldering should not be done more than two times.
2. When soldering, do not put stress on the IRM device during heating.
3. After soldering, do not warp the circuit board.



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1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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